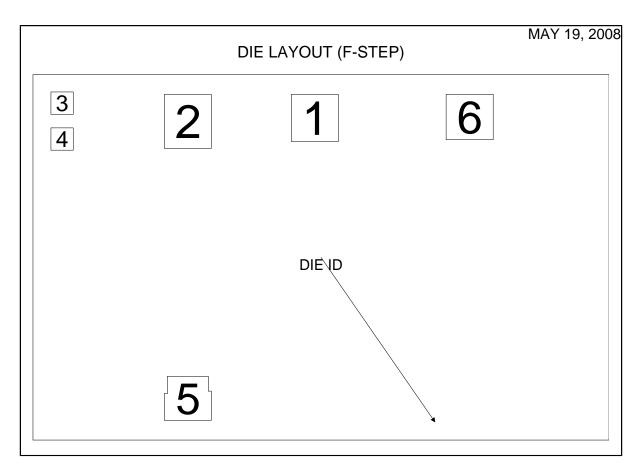


LM140KG-12 MD8 MW8 3-TERMINAL POSITIVE REGULATORS



DIE/WAFER CHARACTERISTICS

DIE/WAFER CHARA	CTERISTICS					
Fabrication Attributes		General Die Information				
Physical Die	140F	Bond Pad Opening 193.04µm x 180				
Identification		Size (min)				
Die Step	F	Bond Pad Metalization	AL 0.5%CU			
Physical Attributes		Passivation	PECVDOX NITRIDE			
Wafer Diameter	150mm	Back Side Metal	Gold			
Die Size (Drawn)	2362.2µm x 1498.6µm	Back Side Connection	GND			
	93.0mils x 59.0mils					
Thickness	254µm Nominal					
Min Pitch	520.70μm					
Note: All values are round	ded to the nearest micron	•				
Special Assembly Requirements:						



LM140KG-12 MD8 MW8 3-TERMINAL POSITIVE REGULATORS

(Referenced t	Die Bond Pad Coord odie center, coordinates in			U. = Not Us	sed	
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
OUTPUT	1	-25	571	193	Х	193
OUTPUT	2	-546	557	193	Χ	220
NC	3	-1061	632	91	Χ	91
NC	4	-1061	485	91	Χ	91
INPUT	5	-546	-577	193	Χ	180
GND	6	609	575	193	х	185



LM140KG-12 MD8 MW8 3-TERMINAL POSITIVE REGULATORS

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